

SC85410EPXAGC :Part Detail

General Information

Package Information

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Operating Characteristics

Reliability Data Lookup

General Information

Part Number	SC85410EPXAGC
Description	PQ 3 LITE 8555E
Product Line	SCV8517E
PTI	NPAA
Material Type	Tested Packaged Device
Life Cycle Description (code)	NOT RECOMMENDED(DECLINING)
Status	Not Recommended for New Design
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	FCPBGA 575
Package Description and Mechanical Drawing	FCPBGA 575 25SQ*3.75P1.0
Device Weight(g)	3.45280
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	25.000
Package Width (nominal)(mm)	25.000
Package Thickness (nominal)(mm)	3.750
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	No
RoHS Compliant	No
RoHS technical exemption(s)	15
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report
RoHS Certificate of Analysis (CoA)	Contact Us
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS

Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement

Manufacturing Information

Micron Size(μm)	.13
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Ordering Information

Minimum Package Quantity (MPQ)	44
MPQ Container	TRAY
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	220
POQ Container	BOX
Export Control Classification Number (US)	5A002
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency	-

Order

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
14645C	Update Notification	ANNOUNCING QUALIFICATION OF SUBSTRATE MATERIALS FOR MPC8560/8540 AND MPC8555/8541 PRODUCT FAMILIES	16 Sep 2011	15 Dec 2011
14645B	Update Notification	UPDATE TO QUALIFICATION OF SUBSTRATE MATERIALS FOR MPC8560/8540 and MPC8555/8541 PRODUCT FAMILIES	29 Aug 2011	15 Dec 2011
14645A	Update Notification	UPDATE TO QUALIFICATION OF SUBSTRATE MATERIALS FOR MPC8560/8540, MPC8555/8541 AND MPC755/745 PRODUCT FAMILIES	20 Jun 2011	14 Nov 2011
14645	Product Change Notice	Qualification of Substrate Materials for MPC8560/8540, MPC8555/8541 and MPC755/745 Product Families	16 May 2011	106 Sep 2011

14344	Product Bulletin	ERRATUM: E500 CORE ERRONEOUS FLOATING POINT EXCEPTION	20 Oct 2010 21 Oct 2010
14081	Product Change Notice	Addition of Nickel Bump and Second Lid Supplier for MPC8540/8560 & MPC8541/8555	18 May 201016 Aug 2010
13327	Product Bulletin	REFERENCE MANUAL UPDATE - LBCR[AHD] BIT FIELD DESCRIPTION CORRECTION	22 Oct 2008 23 Oct 2008
12970	Product Change Notice	PQ37L HVST FROM FINAL TEST TO PROBE	02 Nov 2007 31 Jan 2008
12877	Product Change Notice	ADD SUPPLIERS FOR MPC8560/40/41/55	20 Sep 200719 Dec 2007
12796	Product Change Notice	PQ37/37L HARDWARE SPEC UPDATE FOR PCI	17 Aug 2007 15 Nov 2007
12471	Product Change Notice	POWERQUICC 37LITE PRODUCT TEST EXPANSION	21 Dec 200621 Mar 2007
12439	Product Change Notice	PQ3 TEST PROGRAM ENHANCEMENT	06 Dec 200606 Mar 2007
12397	Product Change Notice	MPC8540/41/55/60 POWER SEQUENCING UPDATE	09 Nov 2006 15 Nov 2006
12346	Product Change Notice	SUBSTRATE SOLDER MASK CHANGE	09 Oct 2006 11 Jan 2007
11564	Product Change Notice	NEW SUBSTRATE FOR MPC8560/40, MPC8555/41	07 Dec 200507 Mar 2006
11563	Product Bulletin	NEW SUBSTRATE FOR MPC8555/8541	07 Dec 200508 Dec 2005

Operating Characteristics

Sample Exception Availability	N
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Reliability Data Lookup

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